

ZXMN10A11K
100V N-CHANNEL ENHANCEMENT MODE MOSFET
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = 25^\circ C$
100V	350m Ω @ $V_{GS} = 10V$	3.5A
	450m Ω @ $V_{GS} = 6V$	3.1A

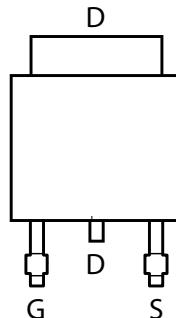
Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

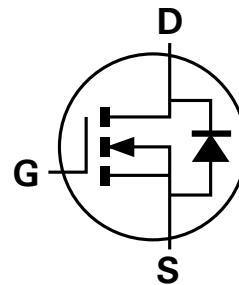
- Motor control
- DC-DC Converters
- Power management functions
- Uninterrupted power supply



Top View



Pin Out – Top View

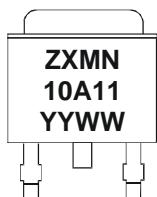


Equivalent Circuit

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN10A11KTC	See Below	13	16	2,500

Note: 1. Diodes, Inc. defines "Green" products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information


ZXMN = Product Type Marking Code, Line 1
 10A11 = Product Type Marking Code, Line 2
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01-52)

ZXMN10A11K
Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source voltage			V_{DSS}	100	V
Gate-Source voltage			V_{GS}	± 20	V
Continuous Drain current	$V_{GS} = 10\text{V}$	(Note 3) $T_A = 70^\circ\text{C}$ (Note 3) (Note 2)	I_D	3.5 2.8 2.4	A
Pulsed Drain current	$V_{GS} = 10\text{V}$	(Note 4)	I_{DM}	9.9	A
Continuous Source current (Body diode)		(Note 3)	I_S	8.4	A
Pulsed Source current (Body diode)		(Note 4)	I_{SM}	9.9	A

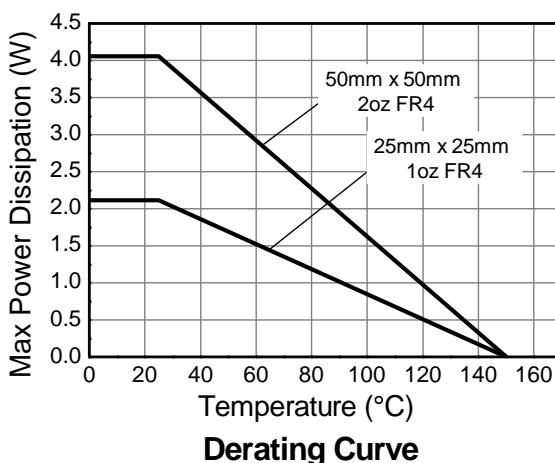
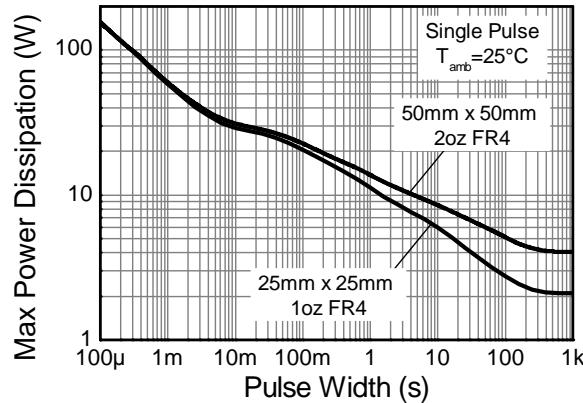
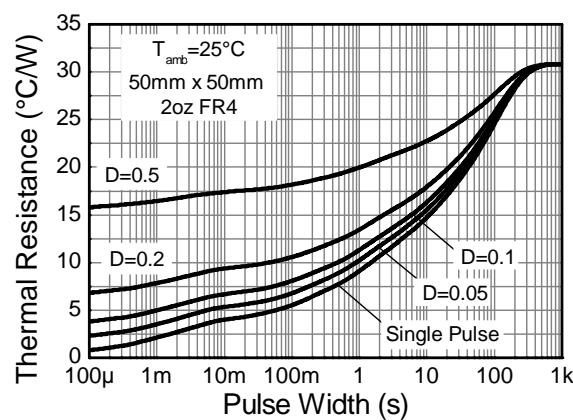
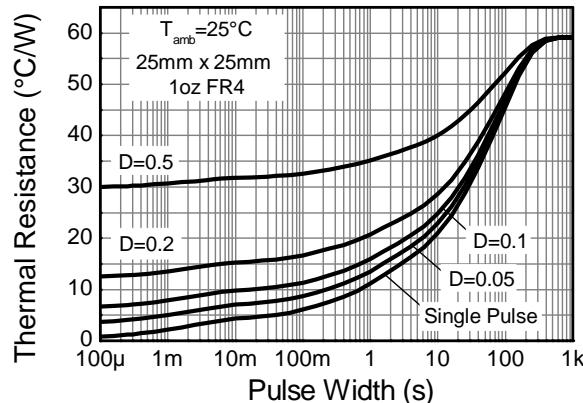
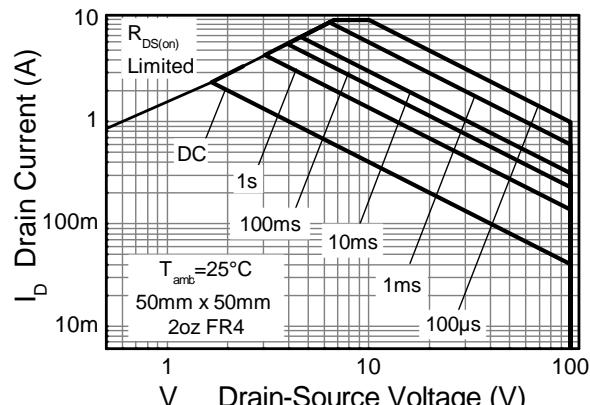
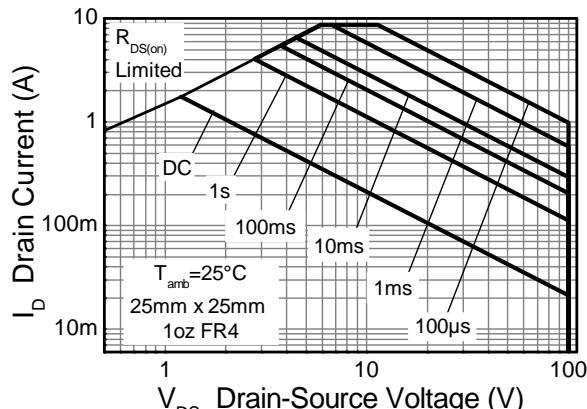
Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation Linear derating factor	(Note 2)	P_D	4.06 32.4	W mW/°C
	(Note 3)		8.5 68.0	
	(Note 6)		2.11 16.8	
Thermal Resistance, Junction to Ambient	(Note 2)	$R_{\theta JA}$	30.8	°C/W
	(Note 3)		14.7	
	(Note 6)		59.1	
Thermal Resistance, Junction to Lead	(Note 5)	$R_{\theta JL}$	1.10	°C/W
Operating and storage temperature range		T_J, T_{STG}	-55 to 150	°C

Notes:

2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
3. Same as note 2, except the device is measured at $t \leq 10$ sec.
4. Same as note 2, except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.
5. Thermal resistance from junction to solder-point (at the end of the drain lead).
6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with the high coverage single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

Thermal Characteristics



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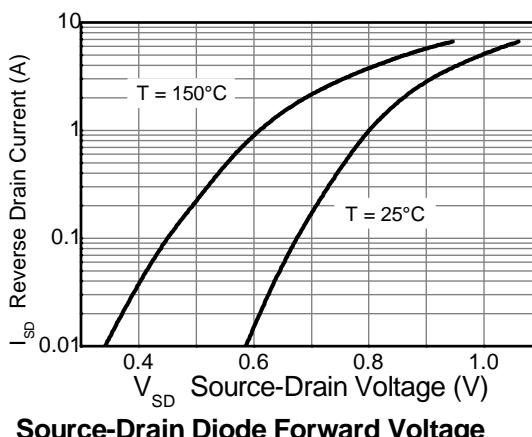
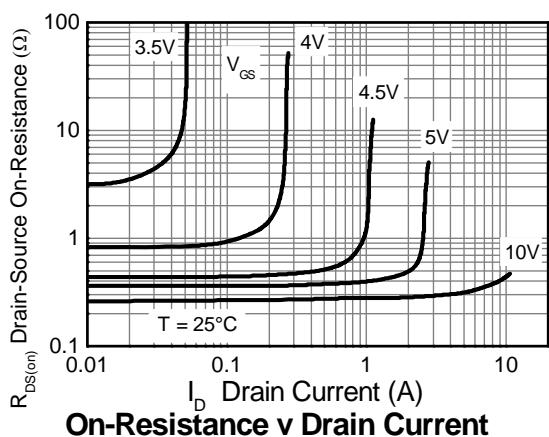
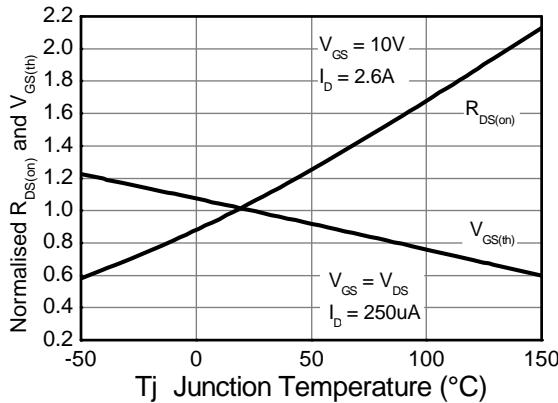
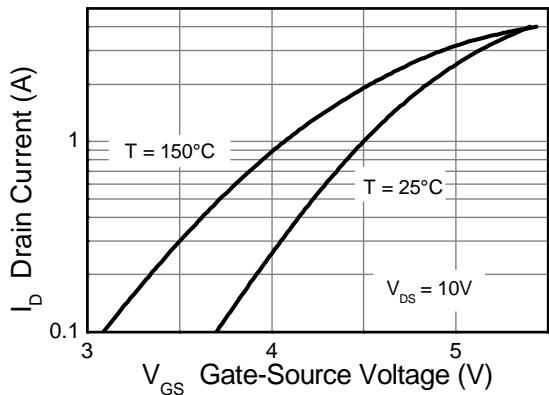
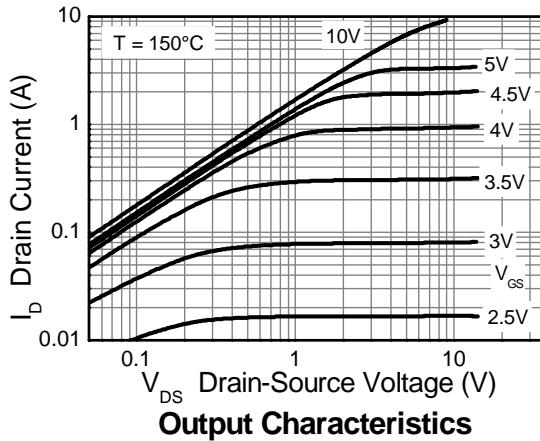
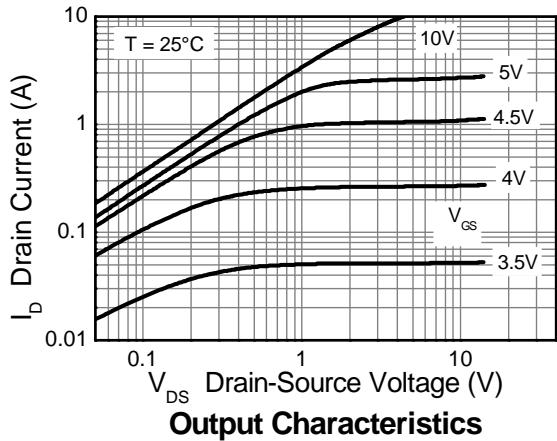
Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	100	—	—	V	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(\text{th})}$	2	—	4	V	$I_D = 250\mu\text{A}, V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 7)	$R_{DS(\text{ON})}$	—	—	0.350	Ω	$V_{GS} = 10\text{V}, I_D = 2.6\text{A}$
			—	0.450		$V_{GS} = 6\text{V}, I_D = 1.3\text{A}$
Forward Transconductance (Notes 7 & 8)	g_{fs}	—	4	—	S	$V_{DS} = 15\text{V}, I_D = 2.6\text{A}$
Diode Forward Voltage (Note 7)	V_{SD}	—	0.850	0.950	V	$I_S = 1.85\text{A}, V_{GS} = 0\text{V}$
Reverse recovery time (Note 8)	t_{rr}	—	26	—	ns	
Reverse recovery charge (Note 8)	Q_{rr}	—	30	—	nC	$I_S = 1.0\text{A}, dI/dt = 100\text{A}/\mu\text{s}$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	274	—	pF	
Output Capacitance	C_{oss}	—	21	—	pF	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}$
Reverse Transfer Capacitance	C_{rss}	—	11	—	pF	$f = 1\text{MHz}$
Total Gate Charge (Note 9)	Q_g	—	3.5	—	nC	$V_{GS} = 6\text{V}$
Total Gate Charge (Note 9)	Q_g	—	5.4	—	nC	
Gate-Source Charge (Note 9)	Q_{gs}	—	1.4	—	nC	$V_{GS} = 10\text{V}$
Gate-Drain Charge (Note 9)	Q_{gd}	—	1.5	—	nC	$I_D = 2.5\text{A}$
Turn-On Delay Time (Note 9)	$t_{D(\text{on})}$	—	2.7	—	ns	
Turn-On Rise Time (Note 9)	t_r	—	1.7	—	ns	
Turn-Off Delay Time (Note 9)	$t_{D(\text{off})}$	—	7.4	—	ns	$V_{DD} = 50\text{V}, V_{GS} = 10\text{V}$
Turn-Off Fall Time (Note 9)	t_f	—	3.5	—	ns	$I_D = 1.0\text{A}, R_G \geq 6\Omega$

Notes:

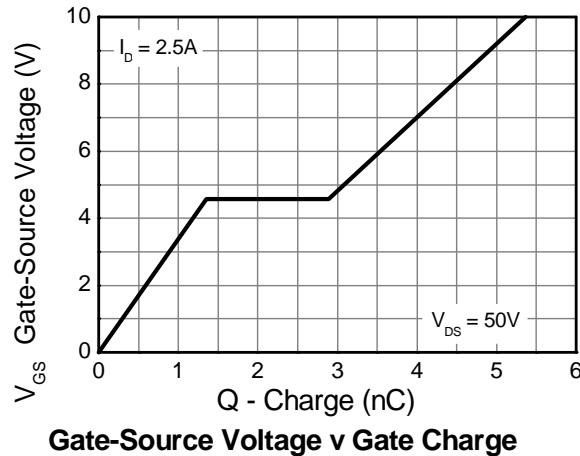
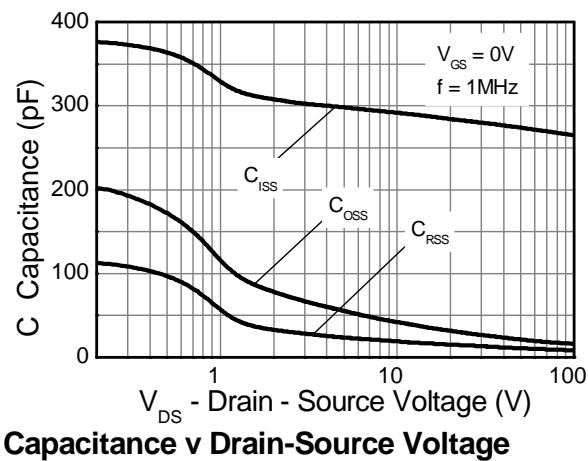
- 7. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$
- 8. For design aid only, not subject to production testing.
- 9. Switching characteristics are independent of operating junction temperatures.

Typical Characteristics

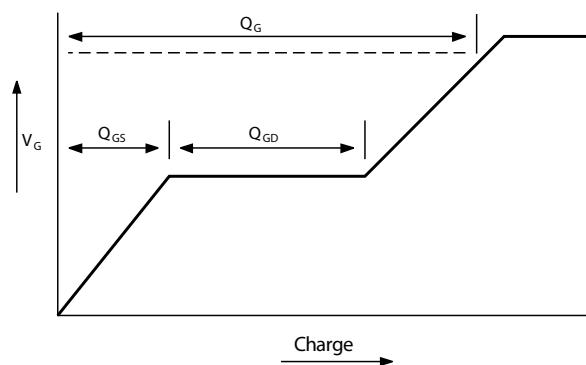


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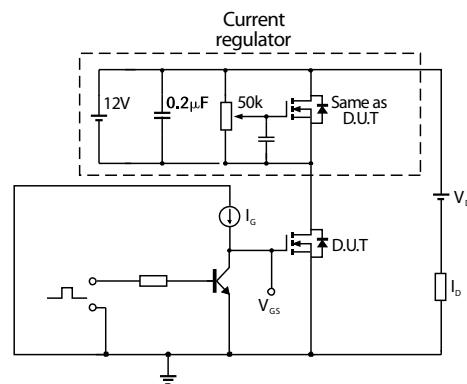
Typical Characteristics - continued



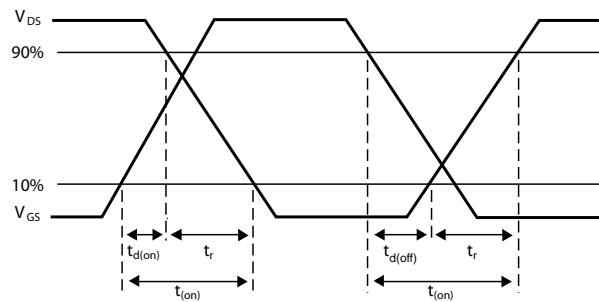
Test Circuits



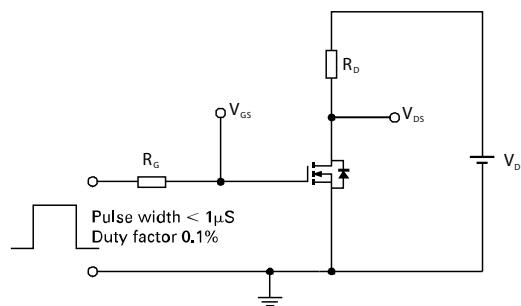
Basic gate charge waveform



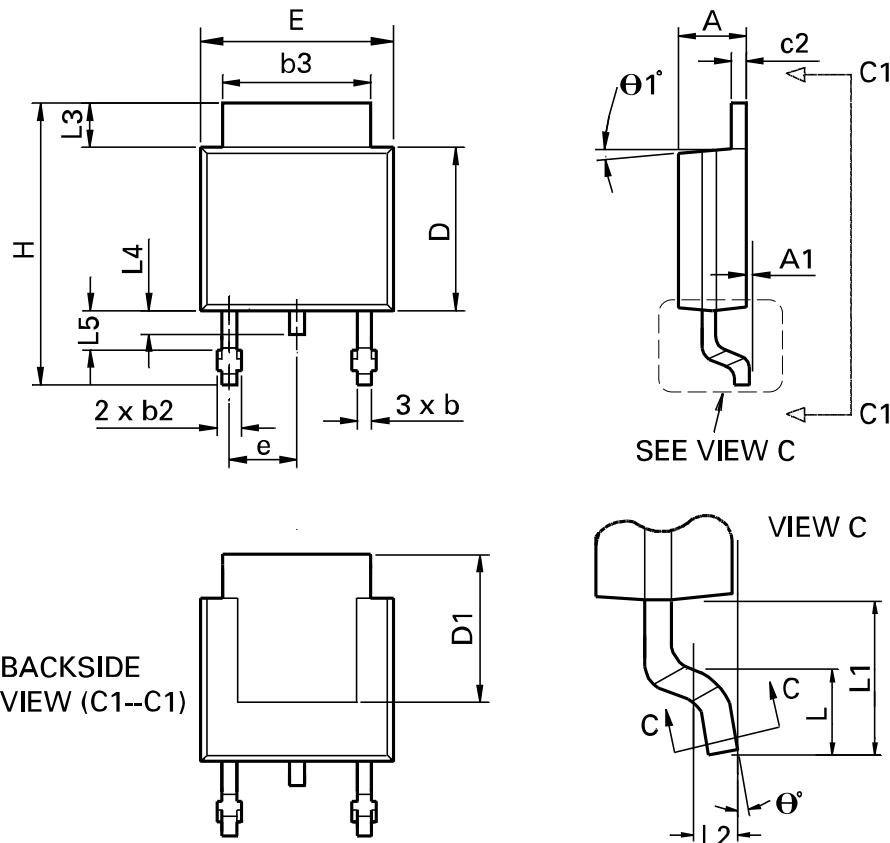
Gate charge test circuit



Switching time waveforms

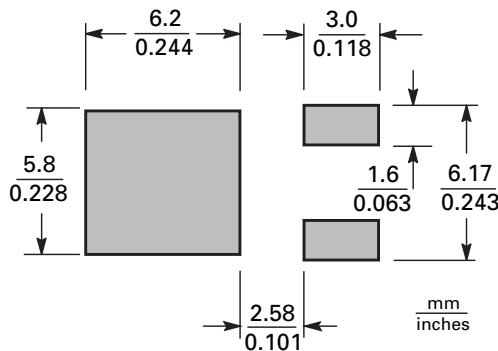


Switching time test circuit

ZXMN10A11K
Package Outline Dimensions


DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.086	0.094	2.18	2.39	e	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	H	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	Θ1°	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	Θ°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-

Suggested Pad Layout



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